hp workstations
j6700 and j6750

data sheet

largest memory, smallest package available

The HP Workstation j6700 and HP Workstation j6750 are flexible, high memory capacity, dual PA-8700 750-MHZ or dual PA-8700+ 875-MHz processor UNIX workstations providing incredible performance for handling very large design files, reducing the total compute time required, and enabling quicker time to market. Whether used as a deskside configuration optimized for your office environment or a racked solution, the HP j6700's and HP's j6750's performance and reliability will satisfy the most demanding user. When you need the capacity for today's toughest designs and simulations with room to spare for tomorrow's even bigger workloads, look to the HP Workstation j6700 and HP Workstation j6750.

flexible, high memory capacity, dual processing performance

rack up to 20 HP j6700 or HP j6750 workstations in a 2 m rack – gain the value of redeployability

features	benefits
dual 750-MHz PA-8700 or dual 875-MHz PA-8700+ processors	puts more compute and visualization power behind EDA and CAE applications and provides higher application performance at a lower price
16-GB SDRAM capacity	supports analysis of larger models and delivers higher application performance with less disk access; largest memory available
2.25-MB on-chip cache	minimizes system latency and enhances system performance delivering greater application speed and throughput
four-way set associative cache	decreases the miss rate of direct mapped cache requiring less disk-to-cache access for instructions and data yielding higher performance
64-bit x 64-bit – operating system and microprocessor	furnishes large address spaces for improved large processing performance such as full-chip simulation, logic synthesis and design rule checking
1.9-GB/s I/O peak performance	provides fast data transfer to I/O for excellent file server performance
efficient rack mountable design	increase system versatility and redeployability with flexible configurations , save space – up to 20 systems per 2 m rack
hp *fxe* graphics card	provides full-featured, 3D capability for universal access to all types of data across diverse, cross-functional teams
hp *fx^{10} pro* graphics card	delivers high-end 3D graphics performance for mechanical design and analysis for greater user productivity and performance
hp Fire GL-UX graphics card	delivers fastest 3D UNIX graphics performance for mechanical design and analysis with greatest user productivity and performance
binary compatibility with future PA-RISC and Intel® Itanium® processors	ensures smooth transition to hp's next-generation high-performance systems, protects your investment in applications, data and systems

hp workstation j6700 and j6750 technical specifications

processor	hp j6700	hp j6750
type	PA-8700	PA-8700+
clock frequency	750-MHz	875-MHz
number of processors	2	2

cache (on-chip)	
total cache	2.25-MB
instruction	0.75-MB
data	1.50-MB

main memory	
bus bandwidth	1.9-GB/s
RAM type	120-MHz ECC SDRAM
capacity	1-MB to 16-GB
memory slots	16 DIMMs

storage bays	1 slim line optical, 2 Ultra 2 SCSI LVD

internal storage (2 bays)	up to 2 devices, 146-GB maximum Ultra 2 SCSI LVD, hot pluggable, 80 pin SCA connector
	18-GB (10K RPM)
	36-GB (10K RPM)
	73-GB (10K RPM)
	36-GB (15K RPM)

external storage	
NSE SCSI (HD50)	1 shared port - up to 7 devices
Ultra2 SCSI LVD	1 shared port - up to 13 devices

removable media	
optical drive	1 slim line, ATAPI interface, DVD or DVD/CD-RW combo drive

expansion slots (3 total)	
PCI 4X (full size)	3 slots, 64-bit 3.3-volt 66-MHz, 20 watts per slot

integrated networking	
LAN data rate	10/100-Mb/s

built-in I/O	
serial interface 9-pin DIN	2 ports
USB (Universal Serial Bus) Series A	2 ports (keyboard and mouse only)

audio	
type	integrated, CD-quality stereo
inputs	stereo line-in, MIC-in
outputs	stereo line-out, internal speaker with frequency range of 25-20,000-Hz, internal CD-ROM audio, headphone

environmental specifications	
altitude	
– operating	0-3000 m (0-10,000 ft)
– non-operating	0-4500 m (0-15,000 ft)
temperature	
– operating	5 to +35 degrees C
– non-operating	-40 to +70 degrees C
humidity	
– operating	15 to 80% (non condensing)
vibration	
– operating random	0.21 G rms, 5-500-Hz
– swept sine survival	0.5 G peak, 5-500-Hz
– random survival	2.09 G rms, 5-500-Hz
safety	UL1950, CUL to CSA C22.2#950, and TUV GS, Mark to EN60950/IEC950
emissions	FCC and CISPR Class A and VCCI Class A

physical dimensions	deskside configuration
height	49.5 cm (19.5 inches)
width	13.7 cm (5.4 inches)
depth	65.5 cm (25.8 inches)
	racked configuration
height	2-EIA units
width	48.3 cm (19.0 inches)
depth	62.2 cm (24.5 inches)
rack orientation	horizontal

net weight	
minimum configuration	18.2 kg (40 lbs.)
fully loaded	21.8 kg (48 lbs.)

power requirements	
input current	6 amps RMS max @ 100-120 V 3 amps RMS max @ 220-240 V
line frequency	50-60-Hz
maximum power input	600 watts (maximum power configuration will vary)

supported operating systems
hp-ux 11i TCOE (Technical Computing Operating Environment)
hp-ux 11i MTOE (Minimal Technical Operating Environment)
hp-ux 11.0

monitors	
hp L2025	20 inch LCD, flat-panel
hp L1325	18 inch LCD, flat-panel
hp wide-aspect	24 inch CRT, flat-screen, wide aspect
hp p1130	21 inch CRT, flat-screen
hp p920	19 inch CRT, flat-screen

leadership graphics—entry 3D	
hp *fxe*	3 maximum, 24-MB FB memory, 9.5-MB maximum texture memory at 1280 x 1024 resolution

leadership graphics—high-end 3D	
hp *fx*^{10} *pro*	2 maximum, 128-MB FB memory, 110-MB maximum texture memory at 1280 x 1024 resolution

leadership graphics—extreme 3D	
hp Fire GL-UX	2 maximum, 128-MB FB memory, 110-MB maximum texture memory at 1280 x 1024 resolution

For more information about the HP leadership graphics program:
www.hp.com/go/leadershipgraphics